

QuantumTM SA.45s CSAC Chip Scale Atomic Clock



With an extremely low power consumption of <120 mW and a volume of <17 cc, the Microsemi SA.45s Chip Scale Atomic Clock (CSAC) brings the accuracy and stability of an atomic clock to portable applications for the first time.

The SA.45s provides 10 MHz and 1 PPS outputs at standard CMOS levels, with short-term stability (Allan Deviation) of $3.0E^{-10}$ @ TAU = 1 sec, typical long-term aging of $<9E^{-10}$ /month, and maximum frequency change of $\pm 5E^{-10}$ over an operating temperature range of -10 °C to 70 °C.

The SA.45s CSAC accepts a 1 PPS input that may be used to synchronize the unit's 1 PPS output to an external reference clock with ± 100 ns accuracy. It also use the 1 PPS input to discipline its phase and frequency to within 1 ns and $1.0E^{-12}$, respectively.

A standard CMOS-level RS-232 serial interface is built in to the SA.45s. This is used to control and calibrate the unit and also to provide a comprehensive set of status monitors. The interface is also used to set and read the CSAC's internal time-of-day clock.



Microsemi invented portable atomic timekeeping with QUANTUM[™], the world's first family of miniature and chip scale atomic clocks.

Choose QUANTUM[™] class for best-inclass stability, size, weight, and power consumption.

Features

- Power consumption <120 mW
- Less than 17 cc volume, 1.6" x 1.39" x 0.45"
- 10 MHz CMOS-compatible output
- 1 PPS output and 1 PPS input for synchronization
- RS-232 interface for monitoring and control
- Short term stability (Allan Deviation) of 3.0E⁻¹⁰@ TAU =1 sec

Applications*

- GPS receivers
- Backpack radios
- Anti-IED jamming systems
- Autonomous sensor networks
- Unmanned vehicles
- Underwater sensor systems
- Stability for various other communication and transmission applications

*The Chip Scale Atomic Clock is not tested, qualified, and rated for space applications



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Options to Meet a Wider Range of Applications

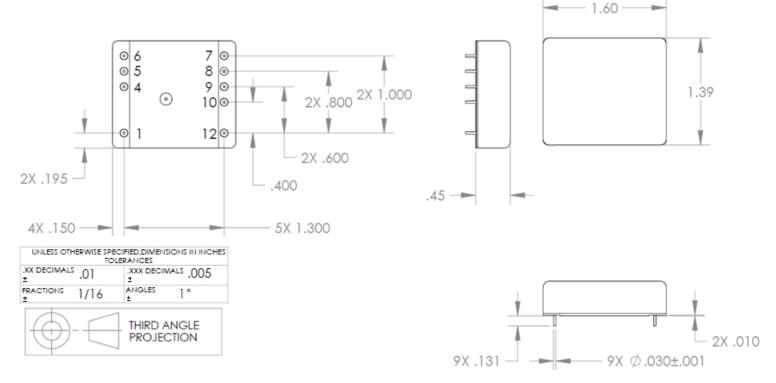
Following are the different SA.45s CSAC options with there output frequencies.

Options	Output Frequency
001	10 MHz
003	16.384 MHz
004	10.24 MHz
006	5 MHz

For other output frequencies please contact Microsemi for details.

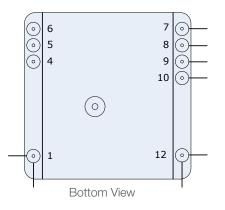
The Chip Scale Atomic Clock is not tested, qualified, and rated for space applications.

Mechanical Interface



Pin Description

Pin Number	I.D.
1	Tune
2	N/A
3	N/A
4	BITE
5	Tx
6	Rx
7	Vcc
8	GND
9	1 PPS IN
10	1 PPS OUT
11	N/A
12	10 MHz OUT





Part number 090-02984-001

Specification

All specifications at 25 °C, V_{cc} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

Frequency	10 MHz
Format	CMOS
Amplitude	$0 V$ to V_{cc}
Load impedance	1 ΜΩ
Quantity	1
1 PPS Output	
•	
Rise/fall time (10%-90%) st load canacitance 10 pE	<10 ns
at load capacitance 10 pF	
Pulse width	100 µs
• Level	0 V to V _{cc}
• Logic High (V _{он}) min	2.80 V
 Logic Low (V_{oL}) max 	0.30 V
 Load impedance 	1 ΜΩ
Quantity	1
1 PPS Input	
Format	Rising edge
Low level	<0.5 V
High level	2.5 V to Vcc
Input impedance	1 MΩ
Quantity	1
Serial Communications	
Protocol	RS232
Format	CMOS 0 V to V _{cc}
• Tx/Rx impedance	1 ΜΩ
Baud rate	57600
Built-in Test Equipment (BITE)	output
Format	CMOS 0 V to Vcc
 Load impedance 	1 ΜΩ
• Logic	0 = Normal operation
	1 = Alarm
Power Input	
Operating	<120 mW
• Warmup	<140 mW
 Input voltage (V_{cc}) 	3.3 ± 0.1 VDC
Physical Specifications	
Size	1.6" x 1.39" x 0.45"
Weight	<35 g
• MTBF	>100,000 hours
Environmental Specification	
Operating	
1 0	
Operating temperature	–10 °C to 70 °C

•	Maximum frequency change
	over operating temp range

 (max. rate of change 0.5 °C/minute) Frequency change over allowable input voltage range Magnetic sensitivity (≤2.0 Gaus Radiated emissions 	Compliant to FCC part 15,
Vibration	Class B, when mounted properly onto host PCB. Maintains lock under MIL-STD-810, Method 514.5, Procedure 1, 7.7 grms
Humidity	0 to 95% RH per MIL-STD-810, Method 507.4.
Storage and Transport (non-o	perating)
Temperature	–55 °C to 85 °C
Shock (1 ms half-sine)	1000 g
Vibration	MIL-STD-810, Method 514.5, Procedure 1, 7.7 grms
Performance Parameters	
Stability (Allan Deviation) ADE	V
• TAU = 1 sec	3.0x10 ⁻¹⁰
• TAU = 10 sec	1.0x10 ⁻¹⁰
• TAU = 100 sec	3.0x10 ⁻¹¹
• TAU = 1000 sec	1.0x10 ⁻¹¹
RF Output Phase Noise (SSB)	
• 1 Hz	<–50 dBc/Hz
• 10 Hz	<-70 dBc/Hz
• 100 Hz	<-113 dBc/Hz
• 1000 Hz	<-128 dBc/Hz
• 10000 Hz	<–135 dBc/Hz
• 100,000 Hz	<–140 dBc/Hz
Frequency Accuracy	
Maximum offset at shipment	±5x10 ⁻¹¹
Maximum retrace (48 hrs off)	$\pm 5 \times 10^{-10}$
 Aging, monthly* 	<9x10 ⁻¹⁰ typical**
 Aging, yearly* 	<1x10 ⁻⁸ typical**
• 1 PPS Sync.	±100 ns
(*After 30 days of continuous or	peration)
Digital Tuning	,
Range	±2x10 ⁻⁸
Resolution	1x10 ⁻¹²
Analog Tuning	
Range	+2.2x10 ⁻⁸
Resolution	1×10^{-11}
Input	0-2.5 V into 100 kΩ
Warm-up Time	<180 s
-	1000
Solder	

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)

** All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.



Part number 090-02984-003

Specification

All specifications at 25 °C, V_{cc} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

Th Output	
Frequency	16.384 MHz
Format	CMOS
Amplitude	0 V to V _{cc}
Load impedance	1 MΩ
Quantity	1
1 PPS Output	
 Rise/fall time (10%-90%) at 	
load capacitance 10 pF	<10 ns
Pulse width	97.656 µs
Level	0 V to V _{cc}
• Logic High (Vон) min	2.80 V
Logic Low (VoL) max	0.30 V
Load impedance	1 MΩ
Quantity	1
1 PPS Input	
Format	Rising edge
Low level	<0.5 V
High level	2.5 V to V _{cc}
Input impedance	1 MΩ
Quantity	1
Serial Communications	1
Protocol	RS-232
 Format 	CMOS 0 V to Vcc
Tx/Rx impedance	1 MΩ
Baud rate	57600
Built-in Test Equipment (BITE)	-
• Format	CMOS 0 V to Vcc
Load impedance	1 MΩ
• Logic	0 = Normal operation
	1 = Alarm
Power Input	
Operating	<120 mW
• Warmup	<140 mW
 Input Voltage (Vcc) 	3.3 ± 0.1 VDC
Physical Specifications	
• Size	1.6" x 1.39" x 0.45"
• Weight	<35 g
• MTBF	>100,000 hours

Environmental Specification

Operating

Maximum frequency change
 over operating temp range

(max. rate of change	
0.5 °C/minute)	$\pm 5 \times 10^{-10}$
 Frequency change over 	
allowable input voltage range	$\pm 4 \times 10^{-10}$
 Magnetic sensitivity (≤2.0 Gauss 	
 Radiated emissions 	Compliant to FCC part 15,
	Class B, when mounted
	properly onto host PCB.
Vibration	Maintains lock under MIL-STD-810, Method 514.5,
	Procedure 1, 7.7 grms
Humidity	0 to 95% RH per
Harmany	MIL-STD-810, Method 507.4.
Storage and Transport (non-op	
Temperature	–55 °C to 85 °C
 Shock (1 ms half-sine) 	1000 g
Vibration	MIL-STD-810, Method 514.5,
VIDIATION	Procedure 1, 7.7 grms
Performance Parameters	riocodalo I, III gillio
Stability (Allan Deviation) ADE	
• TAU = 1 sec	3.0x10 ⁻¹⁰
• TAU = 10 sec	1.0x10 ⁻¹⁰
• TAU = 100 sec	3.0x10 ⁻¹¹
• TAU = 1000 sec	1.0x10 ⁻¹¹
RF Output Phase Noise (SSB)	
• 1 Hz	<–46 dBc/Hz
• 10 Hz	<–66 dBc/Hz
• 100 Hz	<–110 dBc/Hz
• 1000 Hz	<–128 dBc/Hz
• 10000 Hz	<–135 dBc/Hz
• 100,000 Hz	<–140 dBc/Hz
Frequency Accuracy	
 Maximum offset at shipment 	±5x10 ⁻¹¹
• Maximum retrace (48 hrs off):	±5x10 ⁻¹⁰
 Aging, monthly* 	<9x10 ⁻¹⁰ typical**
 Aging, yearly* 	<1x10 ⁻⁸ typical**
• 1 PPS Sync.	±100 ns
(*After 30 days of continuous op	eration)
Digital Tuning	
Range	±2x10 ⁻⁸
Resolution	1x10 ⁻¹²
Analog Tuning	
Range	±2.2x10 ⁻⁸
Resolution	1x10 ⁻¹¹
Input	0-2.5 V into 100 kΩ
Warm-up Time	<180 s
•	< 100 S
Solder	

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)

** All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.



Part number 090-02984-004

Specification

All specifications at 25 °C, V_{cc} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

Frequency	10.24 MHz
Format	CMOS
Amplitude	0 V to V _{cc}
Load impedance	1 ΜΩ
Quantity	1
1 PPS Output	
 Rise/fall time (10%-90%) at 	
load capacitance 10 pF	<10 ns
 Pulse width 	100 µs
• Level	0 V to V _{cc}
• Logic High (Vон) min	2.80 V
Logic Low (VoL) max	0.30 V
 Load impedance 	1 MΩ
Quantity	1
1 PPS Input	
 Format 	Rising edge
Low level	<0.5 V
High level	2.5 V to Vcc
Input impedance	1 MO
Quantity	1
Serial Communications	
Protocol	RS-232
Format	CMOS 0 V to Vcc
 Tx/Rx impedance 	1 MΩ
Baud rate	57600
Built-in Test Equipment (BITE)	
Format	CMOS 0 V to Vcc
Load impedance	1 MΩ
	rmal operation
	1 = Alarm
Power Input	
Operating	<120 mW
• Warmup	<140 mW
 Input Voltage (Vcc) 	3.3 ± 0.1 VDC
Physical Specifications	
• Size	1.6" x 1.39" x 0.45"
Weight	<35 g
• MTBF	>100,000 hours
Environmental Specification	
Operating	
Operating temperature	–10 °C to 70 °C

•	Maximum frequency change
	over operating temp range

(max. rate of change	
0.5 °C/minute)	$\pm 5 \times 10^{-10}$
 Frequency change over 	
allowable input voltage range	$\pm 4 \times 10^{-10}$
 Magnetic sensitivity (≤2.0 Gaus 	s) ±9x10 ⁻¹¹ /Gauss
 Radiated emissions 	Compliant to FCC part 15,
	Class B, when mounted
	properly onto host PCB.
Vibration	Maintains lock under
	MIL-STD-810, Method 514.5,
	Procedure 1, 7.7 grms
Humidity	0 to 95% RH per
	MIL-STD-810, Method 507.4.
Storage and Transport (non-o	
Temperature	–55 °C to 85 °C
 Shock (1 ms half-sine) 	1000 g
Vibration	MIL-STD-810,Method 514.5,
	Procedure 1, 7.7 grms
Performance Parameters	
Stability (Allan Deviation) ADE	V
• TAU = 1 sec	3.0x10 ⁻¹⁰
• TAU = 10 sec	1.0x10 ⁻¹⁰
• TAU = 100 sec	3.0x10 ⁻¹¹
• TAU = 1000 sec	1.0x10 ⁻¹¹
RF Output Phase Noise (SSB)	
 1 Hz 	<–50 dBc/Hz
• 10 Hz	<-70 dBc/Hz
• 100 Hz	<-113 dBc/Hz
 100112 1000 Hz 	<-128 dBc/Hz
• 1000 Hz	<-135 dBc/Hz
 100,000 Hz 	< 100 dBc/Hz <-140 dBc/Hz
Frequency Accuracy	5 4 6 11
Maximum offset at shipment	±5x10 ⁻¹¹
Maximum retrace (48 hrs off)	$\pm 5 \times 10^{-10}$
 Aging, monthly* 	<9x10 ⁻¹⁰ typical**
Aging, yearly*	<1x10 ⁻⁸ typical**
• 1 PPS Sync.	±100 ns
(*After 30 days of continuous op	peration)
Digital Tuning	
Range	±2x10 ⁻⁸
Resolution	1x10 ⁻¹²
Analog Tuning	
Range	±2.2x10 ⁻⁸
Resolution	1x10 ⁻¹¹
• Input	0-2.5 V into 100 kΩ
Warm-up Time	<180 s
Solder	
Hand colder using 62/27 Tip/La	ad Salder with maximum

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)

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Part number 090-02984-006

Specification

All specifications at 25 °C, V_{cc} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

RF Output	
Frequency	5 MHz
Format	CMOS
Amplitude	0 V to V _{cc}
Load impedance	1 MΩ
Quantity	1
1 PPS Output	
• Rise/fall time (10%-90%) at	
load capacitance 10 pF	<10 ns
Pulse width	100 µs
• Level	0 V to V _{cc}
• Logic High (Vон) min	2.80 V
 Logic Low (VoL) max 	0.30 V
Load impedance	1 MΩ
Quantity	1
1 PPS Input	
Format	Rising edge
Low level	<0.5 V
High level	2.5 V to V _{cc}
 Input impedance 	1 MΩ
Quantity	1
Serial Communications	
Protocol	RS-232
Format	CMOS 0 V to Vcc
 Tx/Rx impedance 	1 MΩ
Baud rate	57600
Built-in Test Equipment (BITE)	output
Format	CMOS 0 V to Vcc
Load impedance	1 MΩ
• Logic	0 = Normal operation
	1 = Alarm
Power Input	
Operating	<120 mW

Operating	<120 mW		
• Warmup	<140 mW		
 Input Voltage (Vcc) 	$3.3 \pm 0.1 \text{ VDC}$		
Physical Specifications			

>100,000 hours

Size 1.6" x 1.39" x 0.45" Weight <35 g

• MTBF

over operating temp range (max. rate of change

Operating

Vibration

Environmental Specification

• Maximum frequency change

• Operating temperature

- 0.5 °C/minute)±5x10⁻¹⁰• Frequency change over
allowable input voltage range±4x10⁻¹⁰
- Magnetic sensitivity (<2.0 Gauss) ±9x10⁻¹¹/Gauss
- Radiated emissions
 Compliant to FCC part 15,
 Class B, when mounted
 properly onto host PCB.
- MIL-STD-810, Method 514.5, Procedure 1, 7.7 grms
 Humidity
 0 to 95% RH per
 - MIL-STD-810, Method 507.4.

Maintains lock under

-10 °C to 70 °C

Storage and Transport (non-operating)

•	Temperature	–55 °C to 85 °C
•	Shock (1 ms half-sine)	1000 g
•	Vibration	MIL-STD-810,Method 514.5,
		Procedure 1, 7.7 grms

Performance Parameters

Stability (Allan Deviation) ADEV

• TAU = 1 sec	3.0x10 ⁻¹⁰
• TAU = 10 sec	1.0x10 ⁻¹⁰
• TAU = 100 sec	3.0x10 ⁻¹¹
• TAU = 1000 sec	1.0x10 ⁻¹¹

RF Output Phase Noise (SSB)

• 1 Hz	<–53 dBc/Hz
• 10 Hz	<–73 dBc/Hz
• 100 Hz	<–116 dBc/Hz
• 1000 Hz	<–131 dBc/Hz
• 10000 Hz	<–138 dBc/Hz
• 100,000 Hz	<–140 dBc/Hz
Frequency Accuracy	
Maximum offset at shipment	±5x10 ⁻¹¹
• Maximum retrace (48 hrs off)	±5x10 ⁻¹⁰

Aging, monthly* <9x10⁻¹⁰ typical**
Aging, yearly* <1x10⁻⁸ typical**

±100 ns

• 1 PPS Sync.

(*After 30 days of continuous operation)



Quantum[™] SA.45s CSAC Option 006 cont.

Part number 090-02984-006

Digital Tuning

- Range
- Resolution 1x10⁻¹²

Analog Tuning

- Range
- ±2.2x10⁻⁸
- 1x10⁻¹¹ Resolution
- Input

<180 s

±2x10⁻⁸

- 0-2.5 V into 100 kΩ
- Warm-up Time

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)



Microsemi Corporate Headquarters

One Enterprise, Aliso Viejo, CA 92656 USA Within the USA: +1 (800) 713-4113 Outside the USA: +1 (949) 380-6100 Fax: +1 (949) 215-4996 Email: sales.support@microsemi.com www.microsemi.com

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